WHAT IS CLAIMED IS:

1. An apparatus comprising:

a circuit board;

a plurality of metal inserts; and

a heat sink having a plurality of mounting holes;

each of the metal inserts including:

at least one lower member soldered to the circuit board; and

an upper portion received in a respective one of the mounting holes of the heat sink and secured to the respective one of the mounting holes by a respective fastener.

2. The apparatus of claim 1, wherein each of the fasteners is received within the upper portion of a respective one of the metal inserts.

3. The apparatus of claim 2, wherein the upper portion of each of the metal inserts is swage-formed by the respective fastener to the respective one of the mounting holes of the heat sink.

4. The apparatus of claim 3, wherein each of the fasteners is a tapered screw.

5. The apparatus of claim 2, wherein the upper portion of each of the metal inserts is held between the respective fastener and the respective one of the mounting holes of the heat sink.

6. The apparatus of claim 1, wherein the upper portion of each of the metal inserts includes a pair of barrel segments which together define a substantially cylindrical space in which the respective fastener is received.

7. The apparatus of claim 1, wherein each of the metal inserts includes a pair of lower members soldered to the circuit board.

8. The apparatus of claim 1, wherein the plurality of metal inserts includes four metal inserts.

9. The apparatus of claim 8, further comprising:

a substantially rectangular plastic frame between the circuit board and the heat sink, the frame having four corners, a respective one of the four metal inserts being mounted at each of the four corners of the frame.

10. An article of manufacture comprising:

a substantially rectangular plastic frame having four corners;

four metal inserts each mounted at a respective one of the four corners of the frame, each of the metal inserts including:

at least one pin-shaped lower member to be soldered to a circuit board; and

an upper portion to be secured to a heat sink.

11. The article of claim 10, wherein the upper portion of each of the metal inserts includes a pair of barrel segments which together define a substantially cylindrical space.

12. The article of claim 11, wherein each of the metal inserts includes a pair of pin-shaped lower members.

13. A method comprising:

soldering a plurality of metal inserts to a circuit board;

installing a heat sink on the soldered metal inserts such that a respective upper portion of each of the metal inserts is inserted into a respective mounting hole of the heat sink; and

driving a respective screw into the respective upper portion of each of the metal inserts to secure the heat sink to the metal inserts.

14. The method of claim 13, further comprising:

before the soldering of the metal inserts, inserting at least one pin-shaped lower member of each of the metal inserts into a respective hole in the circuit board.

15. The method of claim 14, wherein the soldering of the metal inserts includes wave soldering.

16. The method of claim 13, wherein the plurality of metal inserts includes four metal inserts.

17. The method of claim 16, wherein the four metal inserts are mounted in a substantially rectangular plastic frame before the soldering of the metal inserts, each of the four metal inserts being located at a respective corner of the frame.

18. A system comprising:

a circuit board;

a processor mounted on the circuit board;

a plurality of metal inserts; and

a heat sink that is thermally coupled to the processor, the heat sink having a plurality of mounting holes;

each of the metal inserts including:

at least one lower member soldered to the circuit board; and

an upper portion received in a respective one of the mounting holes of the heat sink and secured to the respective one of the mounting holes by a respective fastener.

19. The system of claim 18, wherein each of the fasteners is received within the upper portion of a respective one of the metal inserts.

20. The system of claim 19, wherein the upper portion of each of the metal inserts is swage-formed by the respective fastener to the respective one of the mounting holes of the heat sink.

21. The system of claim 20, wherein each of the fasteners is a tapered screw.

22. The system of claim 19, wherein the upper portion of each of the metal inserts is held between the respective fastener and the respective one of the mounting holes of the heat sink.

23. The system of claim 18, wherein the upper portion of each of the metal inserts includes a pair of barrel segments which together define a substantially cylindrical space in which the respective fastener is received.

24. The system of claim 18, wherein each of the metal inserts includes a pair of lower members soldered to the circuit board.

25. The system of claim 18, wherein the plurality of metal inserts includes four metal inserts.

26. The system of claim 25, further comprising:

a substantially rectangular plastic frame between the circuit board and the heat sink, the frame having four corners, a respective one of the four metal inserts being mounted at each of the four corners of the frame.